

SYSTEM, METHOD AND APPARATUS FOR CONSTRUCTING
A SEMICONDUCTOR WAFER-INTERPOSER USING B-STAGE LAMINATES

ABSTRACT

The present invention provides a number of apparatus and methods for interfacing semiconductor wafers containing a multitude of semiconductor dies, with testing equipment. A substrate is constructed with a B-Stage laminate, and when attached to a semiconductor wafer, greatly improves the processing of semiconductor dies. This allows several manufacturing steps to be eliminated and thus results in improved first pass yields, decreased manufacturing times, and improved cycle times. Additionally, the use of the wafer-interposer enables testing, such as parametric and burn-in, at the wafer level. The use of the B-stage laminate also eliminates the need to produce an extremely flat interposer to match well with the very flat semiconductor wafer.